



Press Release

UNISEM RECORDED RM599.5 MILLION (APPROX. US\$197.5 MILLION) REVENUE, RM17.3 MILLION (APPROX. US\$5.7 MILLION) IN NET INCOME FOR 6 MONTHS IN 2011

Kuala Lumpur, 28 July 2011 – Unisem (M) Berhad today announced results for the second quarter ended 30 June 2011 (**2Q11**).

The Group recorded revenue of RM307.5 million (approx. US\$101.9 million) for 2Q11, 14.5 percent decline from the same quarter a year ago (**2Q10**). For the current quarter the Group achieved net profit of RM11.9 million (approx. US\$3.9 million) compared to RM48.0 million (approx. US\$14.8 million) in 2Q10.

For the first half of the current financial year ended 30 June 2011 (**1H11**), the Group recorded revenue of RM599.5 million (approx. US\$197.5 million), a 13 percent decline from that achieved for the six-month period a year ago (**1H10**). For 1H11, the Group recorded a net profit of RM17.3 million (approx. US\$5.7 million) compared to net profit of RM89.3 million (approx. US\$27.1 million) achieved in 1H10.

The decline in revenue and net profit was principally attributable to decline sales volume and a depreciation in the US\$/RM exchange rate, as compared to the rates that prevailed in 2Q10.

Group earnings before interest, tax, depreciation and amortization (**EBITDA**) for 2Q11 came in at about RM55.4 million (approx. US\$18.4 million), EBITDA margin was about 18 percent. Equipment capacity utilization averaged at about 60 percent for the group in 2Q11. Group capital expenditure incurred in 2Q11 was about RM57.4 million (approx. US\$19.0 million), principally for purchase of equipment for packaging & final test activities and facilitation of cleanroom for Unisem Chengdu and Unisem (M) Berhad.

Commenting on the outlook of the Group, Mr. John Chia Sin Tet, group managing director said, "The Directors expect to see modest growth in the revenue and earnings of the Group in the third and fourth quarter of the financial year."

About Unisem

Unisem is a global provider of semiconductor assembly and test services for many of the world's most successful electronics companies. Unisem offers an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding, a wide range of leadframe and substrate IC packaging, wafer level CSP and RF, analog, digital and mixed-signal test services. Our turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. With approximately 9,500 employees worldwide, Unisem has factory locations in Ipoh, Malaysia; Wales, United Kingdom; Chengdu, People's Republic of China; Batam, Indonesia and Sunnyvale, USA. The company is headquartered in Kuala Lumpur, Malaysia. For more information about the company, its products and services, please visit its website at www.unisemgroup.com.